

# 74HC21

## Dual 4-input AND gate

Rev. 6 — 8 February 2013

Product data sheet

### 1. General description

The 74HC21 is a high-speed Si-gate CMOS device and is pin compatible with low-power Schottky TTL (LSTTL).

The 74HC21 provide the 4-input AND function.

### 2. Features and benefits

- Low-power dissipation
- Complies with JEDEC standard no. 7A
- ESD protection:
  - ◆ HBM JESD22-A114E exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$ .

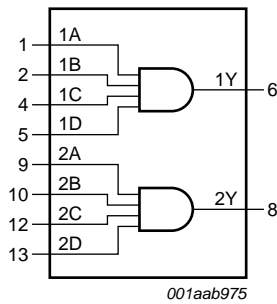
### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC21N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
74HC21D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74HC21DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74HC21PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1

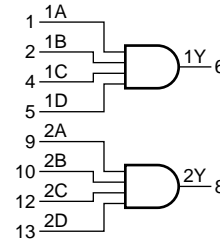


## 4. Functional diagram



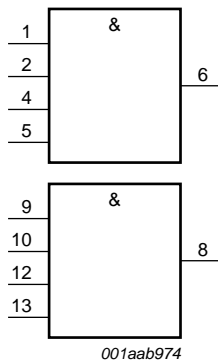
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Fig 1. Functional diagram



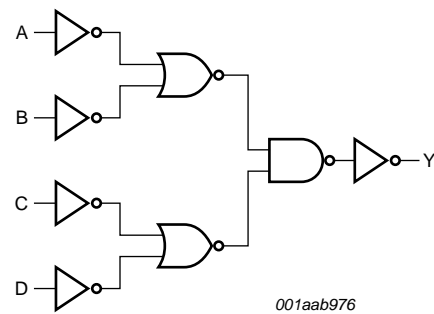
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Fig 2. Logic symbol



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Fig 3. IEC Logic symbol

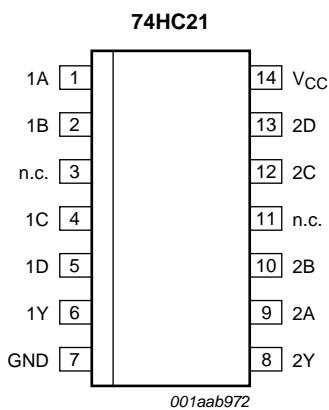


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Fig 4. Logic diagram

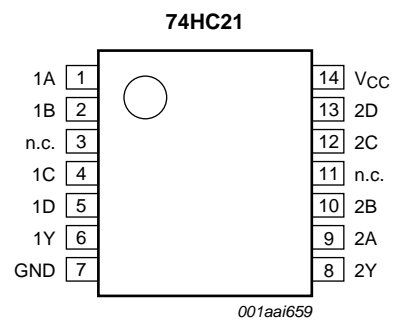
## 5. Pinning information

### 5.1 Pinning



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Fig 5. Pin configuration SOT27-1 and SOT108-1



001aa1659

Fig 6. Pin configuration SOT337-1 and SOT402-1

## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 1B, 1C, 1D	1, 2, 4, 5	data input
n.c.	3, 11	not connected
1Y	6	data output
GND	7	ground (0 V)
2Y	8	data output
2A, 2B, 2C, 2D	9, 10, 12, 13	data input
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input				Output
nA	nB	nC	nD	nY
L	X	X	X	L
X	L	X	X	L
X	X	L	X	L
X	X	X	L	L
H	H	H	H	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	[1] -	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	[1] -	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±25	mA
I <sub>CC</sub>	supply current		-	50	mA
I <sub>GND</sub>	ground current		-50	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation		[2]		
	DIP14 package		-	750	mW
	SO14 and (T)SSOP14 packages		-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP14 package: P<sub>tot</sub> derates linearly with 12 mW/K above 70 °C.  
 For SO14 package: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.  
 For (T)SSOP14 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		2.0	5.0	6.0	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0$ V	-	-	625	ns/V
		$V_{CC} = 4.5$ V	-	1.67	139	ns/V
		$V_{CC} = 6.0$ V	-	-	83	ns/V
$T_{amb}$	ambient temperature		-40	-	+125	°C

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0$ V	1.5	1.2	-	1.5	-	1.5	-	V
		$V_{CC} = 4.5$ V	3.15	2.4	-	3.15	-	3.15	-	V
		$V_{CC} = 6.0$ V	4.2	3.2	-	4.2	-	4.2	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0$ V	-	0.8	0.5	-	0.5	-	0.5	V
		$V_{CC} = 4.5$ V	-	2.1	1.35	-	1.35	-	1.35	V
		$V_{CC} = 6.0$ V	-	2.8	1.8	-	1.8	-	1.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -20$ $\mu$ A; $V_{CC} = 2.0$ V	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20$ $\mu$ A; $V_{CC} = 4.5$ V	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20$ $\mu$ A; $V_{CC} = 6.0$ V	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -4.0$ mA; $V_{CC} = 4.5$ V	3.98	4.32	-	3.84	-	3.7	-	V
		$I_O = -5.2$ mA; $V_{CC} = 6.0$ V	5.48	5.81	-	5.34	-	5.2	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = 20$ $\mu$ A; $V_{CC} = 2.0$ V	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20$ $\mu$ A; $V_{CC} = 4.5$ V	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20$ $\mu$ A; $V_{CC} = 6.0$ V	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0$ mA; $V_{CC} = 4.5$ V	-	0.15	0.26	-	0.33	-	0.4	V
		$I_O = 5.2$ mA; $V_{CC} = 6.0$ V	-	0.16	0.26	-	0.33	-	0.4	V
$I_I$	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0$ V	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu$ A
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0$ V	-	-	2.0	-	20	-	40	$\mu$ A
$C_I$	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

$GND = 0\text{ V}$ ; test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{pd}$	propagation delay	nA, nB, nC or nD to nY; see <a href="#">Figure 7</a> <a href="#">[1]</a>								
		$V_{CC} = 2.0\text{ V}$	-	33	110	-	140	-	165	ns
		$V_{CC} = 4.5\text{ V}$	-	12	22	-	28	-	33	ns
		$V_{CC} = 6.0\text{ V}$	-	10	19	-	24	-	28	ns
		$V_{CC} = 5.0\text{ V}; C_L = 15\text{ pF}$	-	10	-	-	-	-	-	ns
$t_t$	transition time	nY output; see <a href="#">Figure 7</a> <a href="#">[2]</a>								
		$V_{CC} = 2.0\text{ V}$	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5\text{ V}$	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0\text{ V}$	-	6	13	-	16	-	19	ns
$C_{PD}$	power dissipation capacitance	$V_I = GND\text{ to }V_{CC}$ <a href="#">[3]</a>	-	15	-	-	-	-	-	pF

[1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .

[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

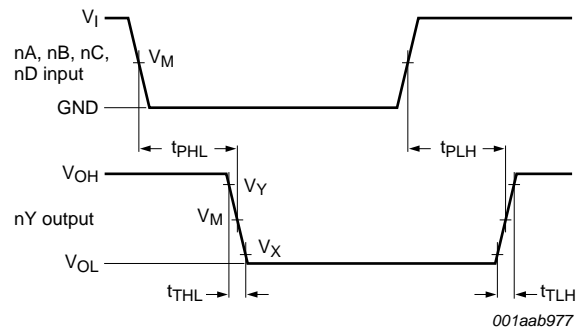
$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in V;

$N$  = number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 11. Waveforms



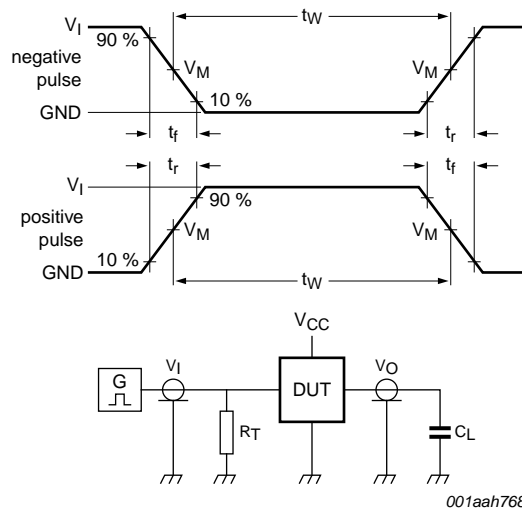
Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. Waveforms showing the input (nA, nB, nC, nD) to output (nY) propagation delays and the output transition times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC21	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = load capacitance including jig and probe capacitance.

**Fig 8. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC21	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

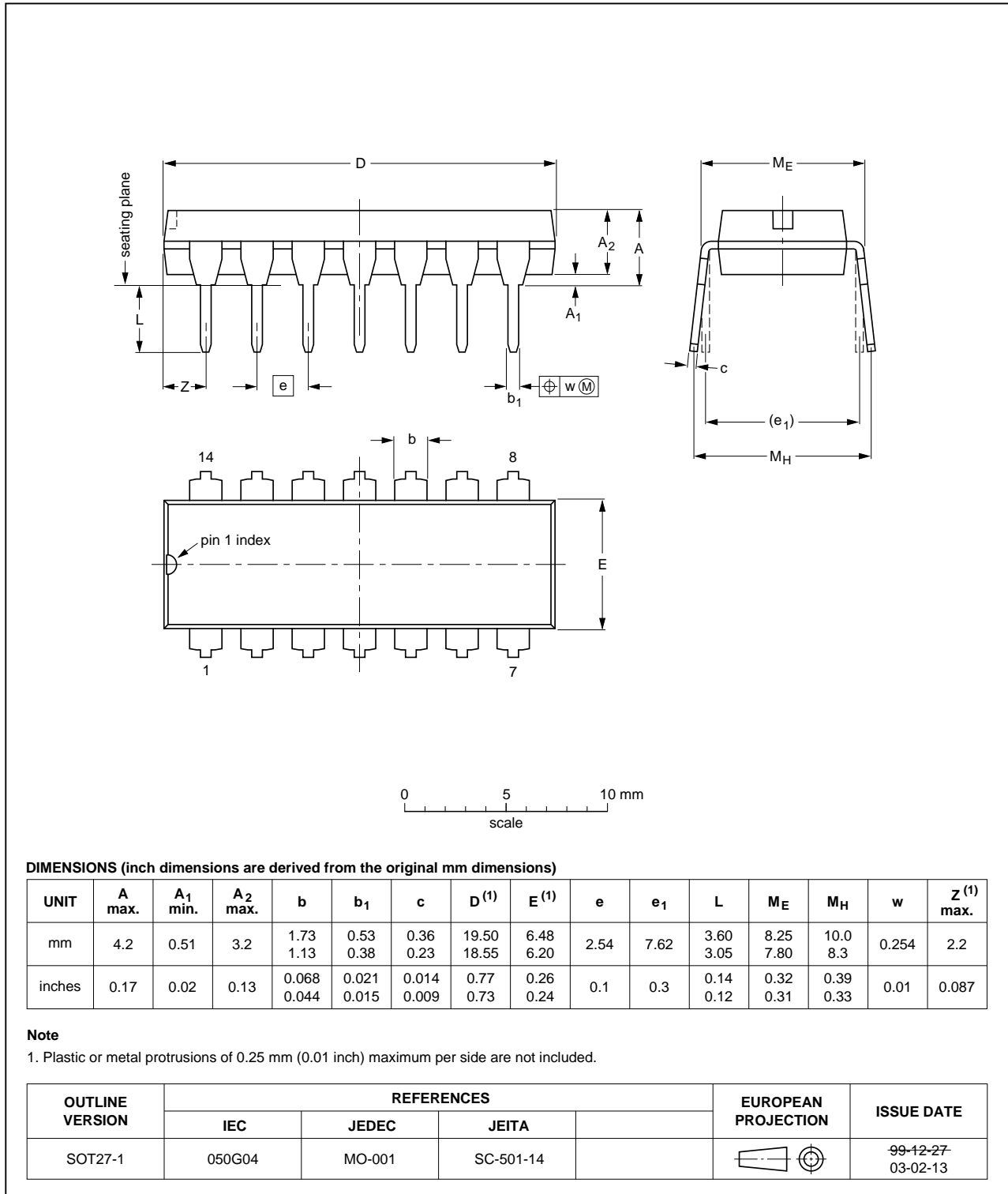


Fig 9. Package outline SOT27-1 (DIP14)



SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

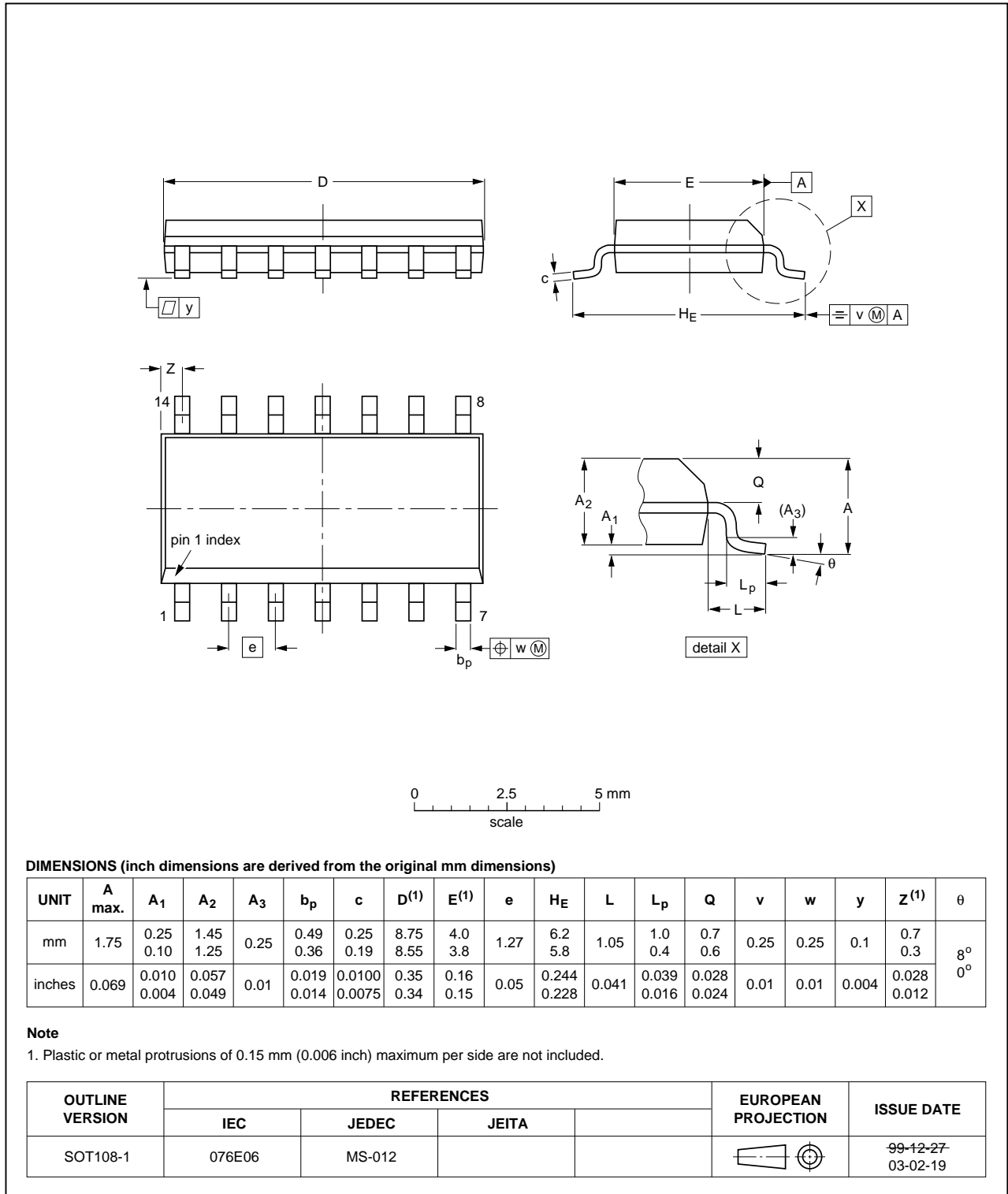


Fig 10. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

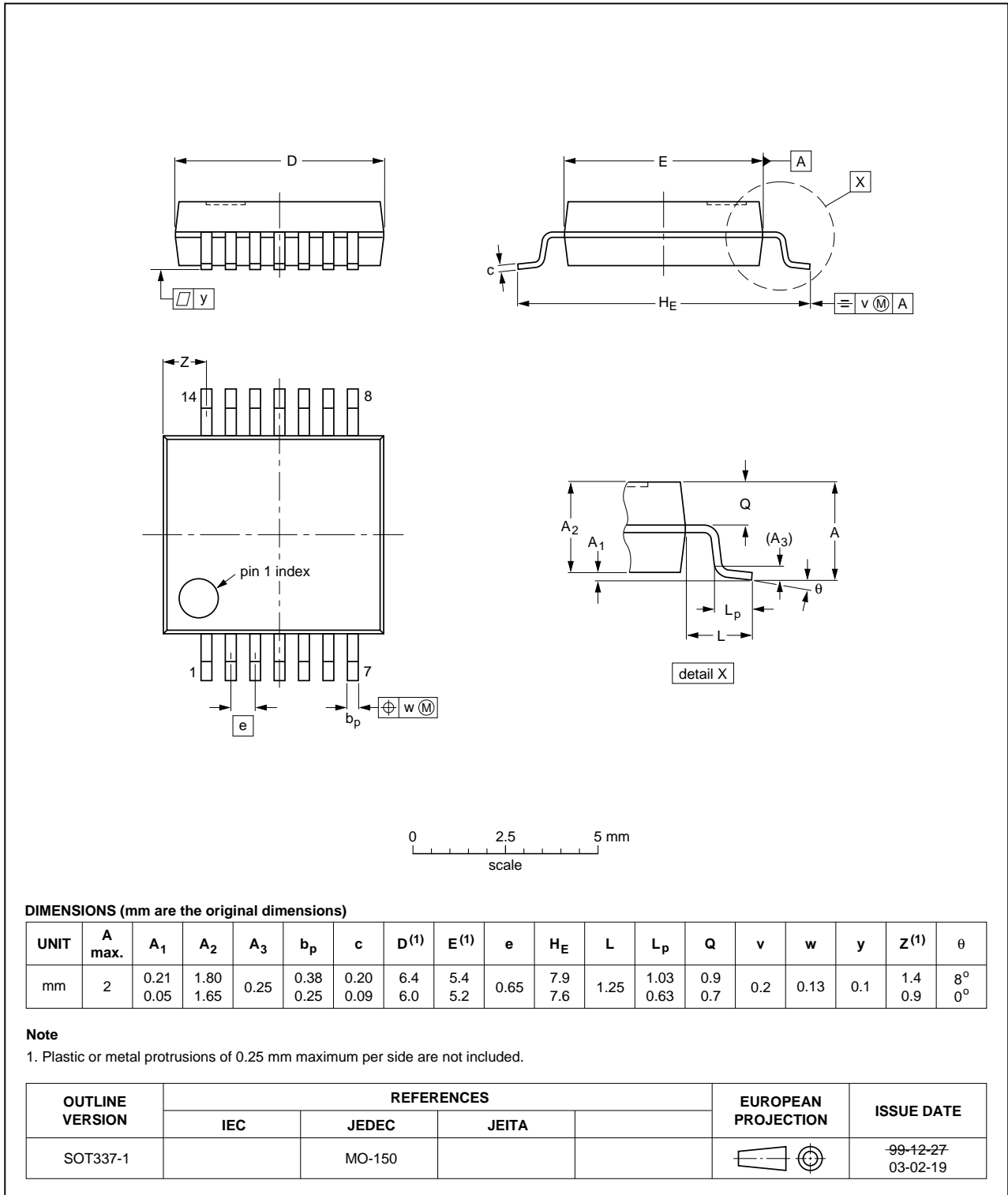


Fig 11. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

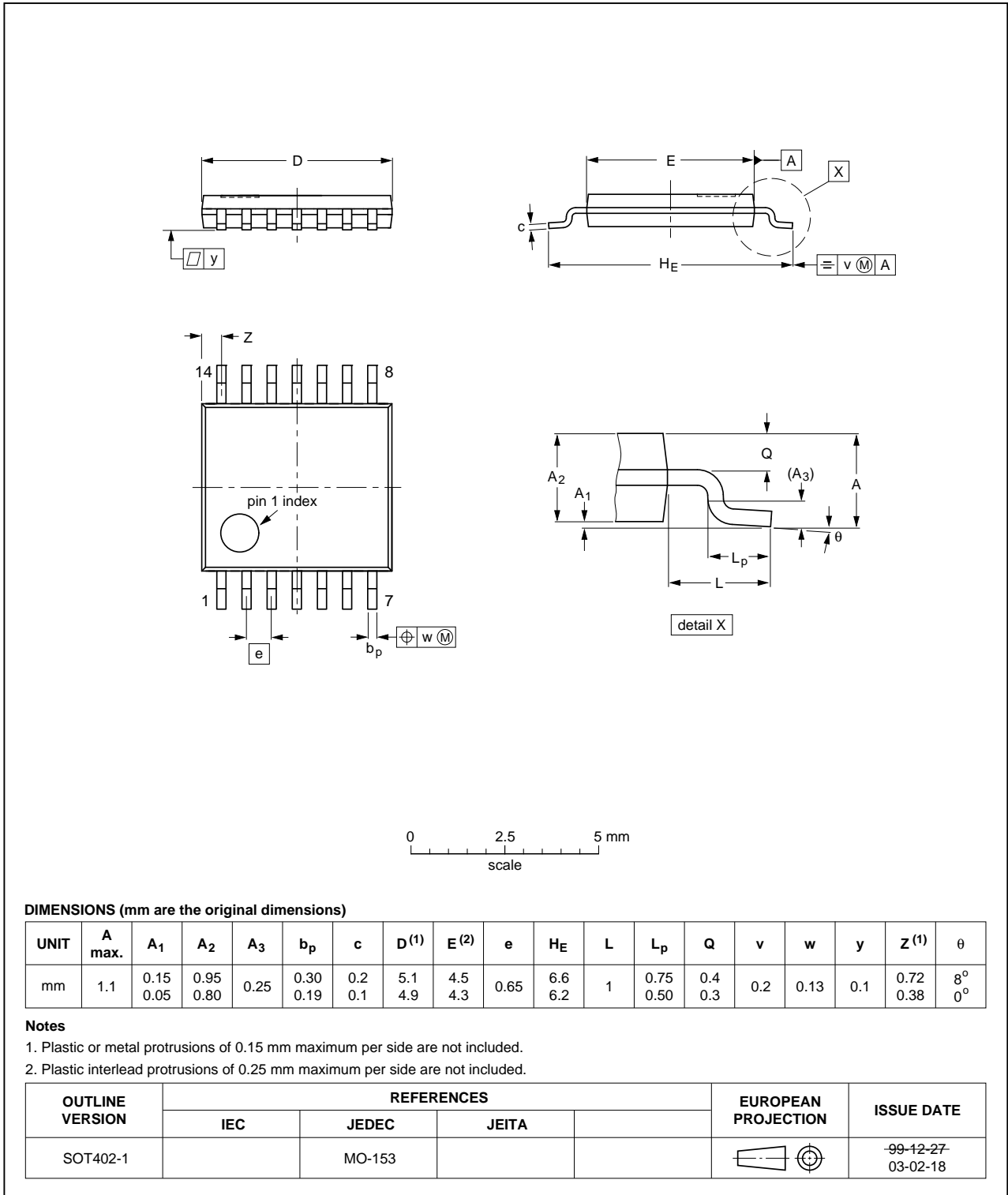


Fig 12. Package outline SOT402-1 (TSSOP14)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC21 v.6	20130208	Product data sheet	-	74HC21 v.5
Modifications:	<a href="#">Section 2</a> : Typo corrected in the specified temperature range.			
74HC21 v.5	20090507	Product data sheet	-	74HC21 v.4
Modifications:	<a href="#">Table 1</a> : Type number 74HCT21PW changed to 74HC21PW.			
74HC21 v.4	20090407	Product data sheet	-	74HC21 v.3
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Added type number 74HC21PW (TSSOP14 package).</li> </ul>			
74HC21 v.3	20041112	Product data sheet	-	74HC_HCT21_CNV v.2
74HC_HCT21_CNV v.2	19970828	Product specification	-	74HC_HCT21 v.1
74HC_HCT21 v.1	19901201	Product specification	-	-

## 15. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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